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SEMICONDUCTOR WAFER MANUFACTURING
METHODS EMPLOYING CLEANING DELAY PERIOD

1/2

Fig. 1

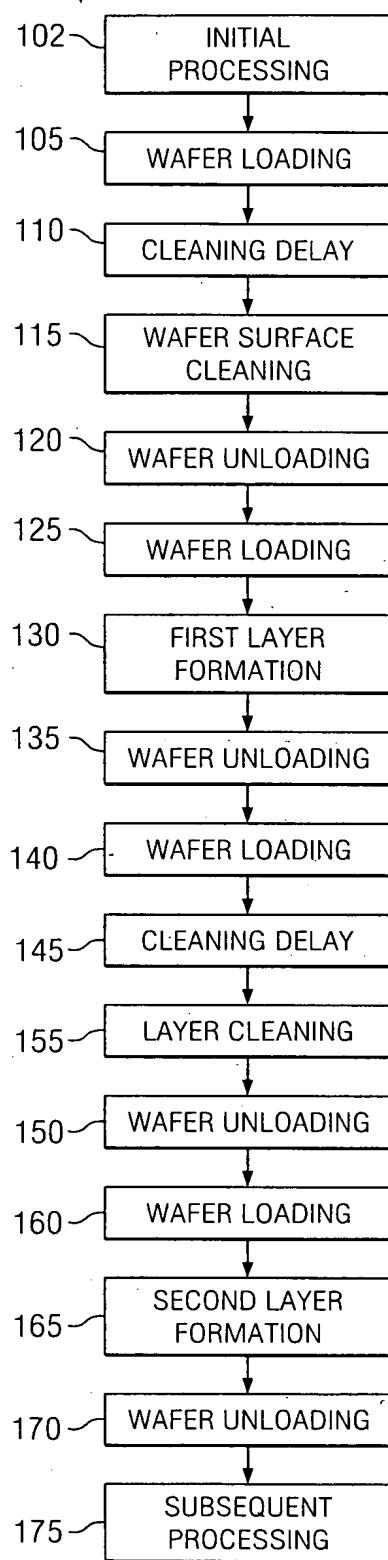
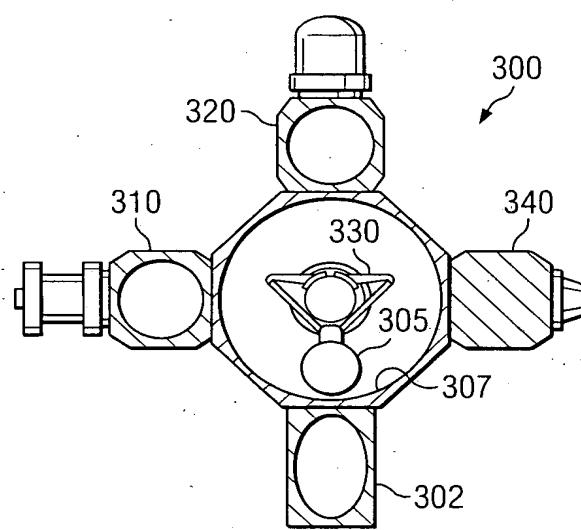


Fig. 3



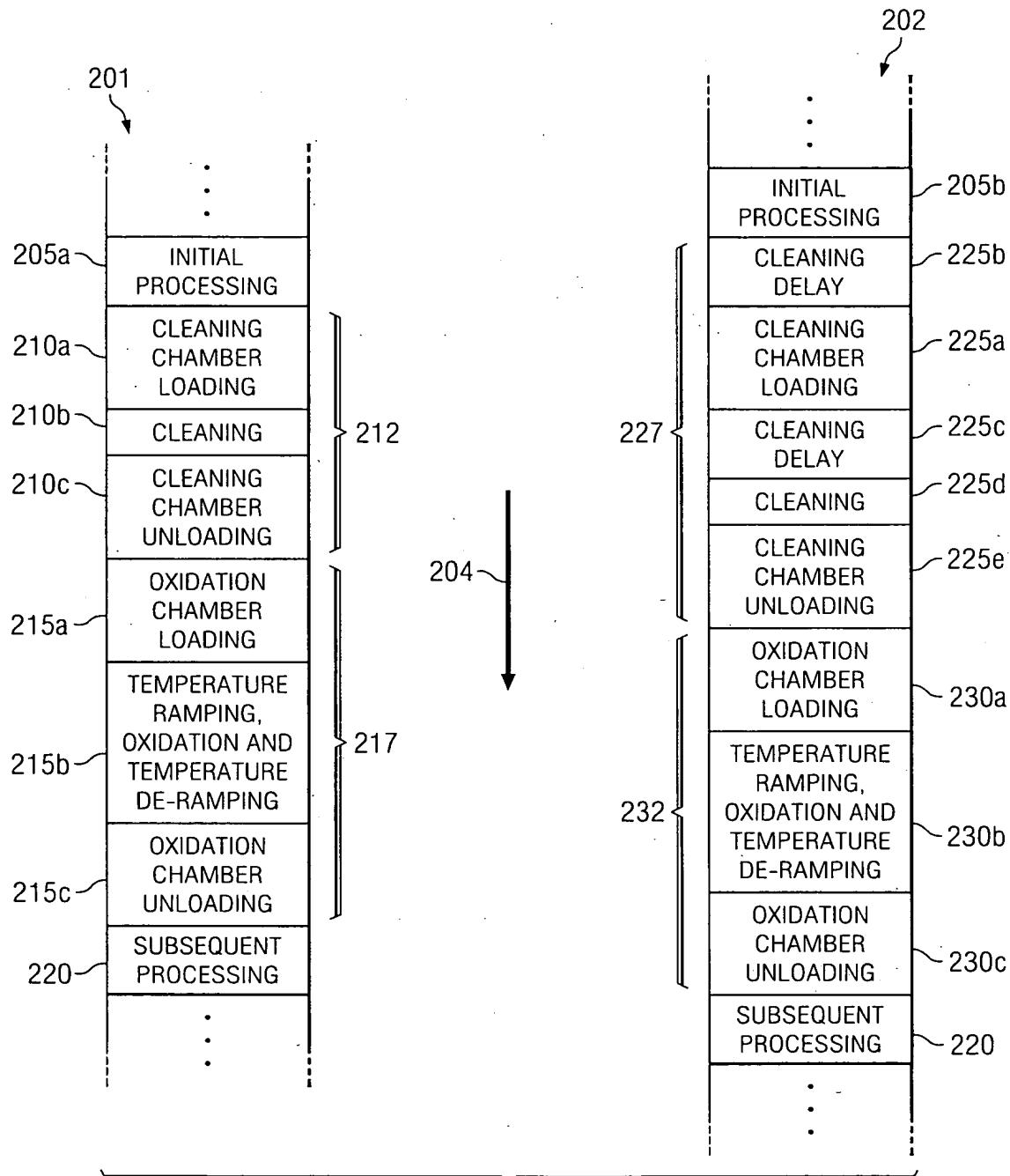


Fig. 2